

Data Sheet 762.5MHz SAW 3030 SPT763M30E

V1.0

Features:

- Ceramic Package for Surface Mounted Technology (SMT)
- RoHS compatible
- Package size 3.00x3.00x1.25mm³
- Electrostatic Sensitive Device(ESD)

Specifications:

- Operation Temperature:-40°C to +85°C
- Compact miniature size
 - 3.0 mm × 3.0 mm footprint
 - 1.25 mm max-height

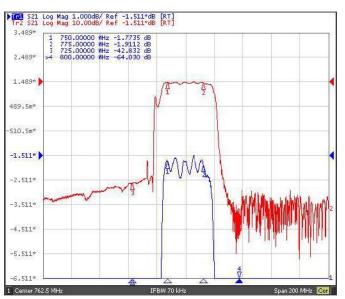
Applications:

- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 25.0 MHz

| Item | | Minimum | Typical | Maximum | Unit |
|--|----|---------|---------|---------|------|
| Center Frequency | fc | | 762.50 | | MHz |
| Insertion Loss(min) | IL | | 1.5 | 2.0 | dB |
| Insertion Loss 750.00 -775.00 MHz | IL | | 2.0 | 3.0 | dB |
| Amplitude Ripple (p-p) 750.00 -775.00 MHz | ∆a | | 0.8 | 1.0 | dB |
| Group Delay Ripple 750.00 -775.00 MHz | | | 45.0 | 100.0 | ns |
| Absolute Attenuation | a | | | | |
| DC- 675.00 MHz | | 40.0 | 45.0 | | dB |
| 675.00 - 725.00 MHz | | 35.0 | 40.0 | | dB |
| 800.00 - 850.00 MHz | | 40.0 | 45.0 | | dB |
| 850.00 - 1500.00 MHz | | 40.0 | 45.0 | | dB |
| Input VSWR 750.00 -775.00 MHz | | | 2.0:1 | 2.2:1 | |
| Output VSWR 750.00 -775.00 MHz | | | 2.0:1 | 2.2:1 | |
| Item | | Minimum | Typical | Maximum | Unit |

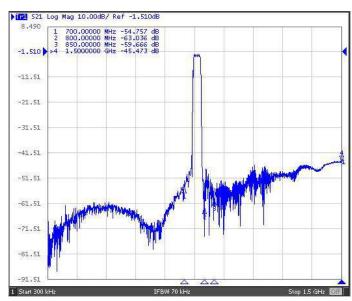
Electrical Specifications. Test Temperature: $25^{\circ}C \pm 2^{\circ}C$

Frequency Characteristics.

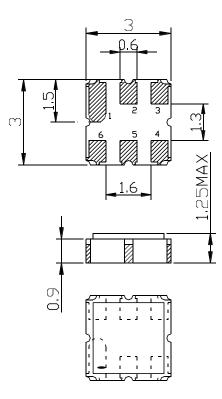


Frequency Response

Frequency Response (wideband)

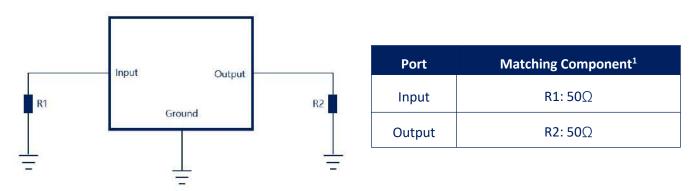


Package & Dimensions



| Pin No. | Description | |
|---------|-------------|--|
| 2 | Input | |
| 5 | Output | |
| 1,3,4,6 | Ground | |

Matching

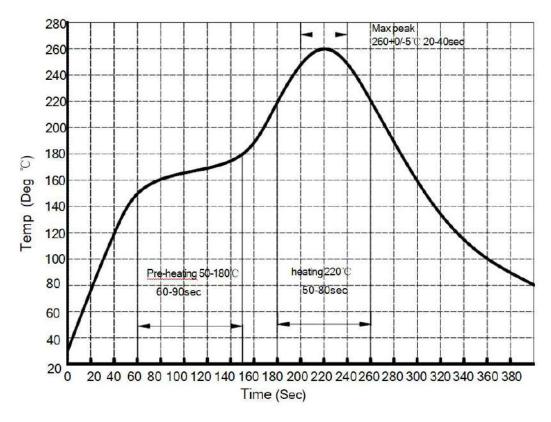


Matching component values shown are recommended based on the Spectron evaluation board. Value adjustment may be required on the end-user's circuit boards for the selected component manufacturer and PCB material.

Maximum Ratings

| Item | | Value | Unit |
|-----------------------|------------------|-----------|------|
| DC Voltage | Vdc | 5 | V |
| Operation Temperature | т | -40 ~ +85 | °C |
| Storage Temperature | T _{stg} | -40 ~ +85 | °C |
| RF Power Dissipation | Р | 20 | dBm |

Recommended Reflow Soldering Diagram



Ordering Information

| Part Number | Number of Devices | Container | |
|-------------|-------------------|---------------|--|
| SPT763M30E | 1000pcs | Tape and Reel | |

Reliability

| No. | Test item | Test condition | |
|-----|---------------------------------|---|--|
| 1 | Temperature Storage | Temperature: $85^{\circ}C\pm 2^{\circ}C$, Duration: 250h, Recovery time: 2h±0.5h (2) Temperature: $-55^{\circ}C\pm 3^{\circ}C$, Duration: 250h, Recovery time: 2h±0.5h | |
| 2 | Humidity Test | Conditions: 60°C±2°C ,90~95% RH Duration: 250h | |
| 3 | Thermal Shock | Heat cycle conditions: TA=-55°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h. | |
| 4 | Vibration Fatigue | Frequency of vibration: 10~55HzAmplitude:1.5mmDirections: X,Y and ZDuration: 2h | |
| 5 | Drop Test | Cycle time: 10 times Height: 1.0m | |
| 6 | Solder Ability Test | Temperature: 245°C±5°CDuration: 3.0s5.0sDepth: DIP2/3 , SMD1/5 | |
| 7 | Resistance to Soldering Heat | (1) Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration: 10±1s (2) Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time : 2 ± 0.5h | |

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